

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-3. (Canceled)

4. (Currently Amended) A semiconductor device comprising:

a substrate;

an adhesive material over the substrate;

a protective film over the adhesive material, said protective film comprising Teflon;

an insulating film over the protective film; and

~~a middle processing component comprising a control section and an operation section, and a memory unit~~ a thin film transistor over the insulating film;

~~wherein the middle processing component includes a thin film transistor of n-channel type and a thin film transistor of p-channel type.~~

5. (Previously Presented) A semiconductor device according to claim 4, wherein the semiconductor device is an authentication card, a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, or a mobile information terminal.

6.-19. (Canceled)

20. (Previously Presented) A semiconductor device comprising:

a substrate;

an adhesive material over the substrate; and

a protective film over the adhesive material;
an insulating film over the protective film;
a middle processing component comprising a control section and an operation section, and a memory unit over the insulating film; and
a battery over the substrate;
wherein the middle processing component includes a thin film transistor of n-channel type and a thin film transistor of p-channel type.

21.-27. (Canceled)

28. (Previously Presented) A semiconductor device comprising:
a plastic substrate;
an adhesive material over the plastic substrate; and
a protective film over the adhesive material, said protective film comprising a material selected from the group consisting of SnO_2 , SrO , Teflon, and metal;
an insulating film over the protective film, said insulating film comprising silicon oxynitride;
a middle processing component comprising a control section and an operation section, and a memory unit over the insulating film; and
a battery over the plastic substrate;
wherein the middle processing component includes a thin film transistor of n-channel type and a thin film transistor of p-channel type.

29. (Previously Presented) A semiconductor device comprising:
a plastic substrate;
an adhesive material over the plastic substrate; and
a protective film over the adhesive material, said protective film comprising a material selected from the group consisting of SnO_2 , SrO , Teflon, and metal;

an insulating film over the protective film;

a middle processing component comprising a control section and an operation section, and a memory unit over the insulating film; and

wherein the middle processing component includes a thin film transistor of n-channel type and a thin film transistor of p-channel type.

30. (Previously Presented) A semiconductor device according to claim 28, wherein the semiconductor device is an authentication card, a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, or a mobile information terminal.

31. (Previously Presented) A semiconductor device according to claim 29, wherein the semiconductor device is an authentication card, a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, or a mobile information terminal.